

FEB 28 2007

Docket No. 740709-507
Application No.: 10/628,240
Page 3 of 15**Amendments to the Abstract**

Please replace the existing Abstract with the following new Abstract.

The invention generally relates to a flexible heat exchanger comprising a pair of flexible multilayer thermoplastic polyimide films each of which comprises an aromatic polyimide substrate film showing no glass transition temperature or a glass transition temperature of 340°C or higher and a thermoplastic aromatic polyimide surface film showing a glass transition temperature in the range of 190 to 300°C in which the surface films of the flexible multilayer thermoplastic polyimide films face each other and are in part fused together, whereby producing between the flexible multilayer thermoplastic polyimide films a conduit pattern through which a fluid passes. The flexible multilayer thermoplastic polyimide films preferably have a thickness in the range of 10 to 125 μm and comprise a linear expansion coefficient of MD, a linear expansion coefficient of TD and an average of linear expansion coefficients of MD and TD, in the range of 10×10^{-6} to 35×10^{-6} cm/cm/°C at 50-200°C.